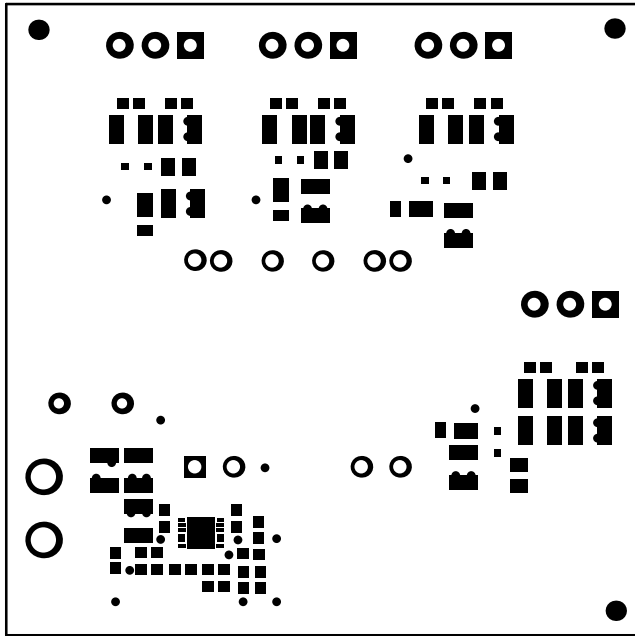
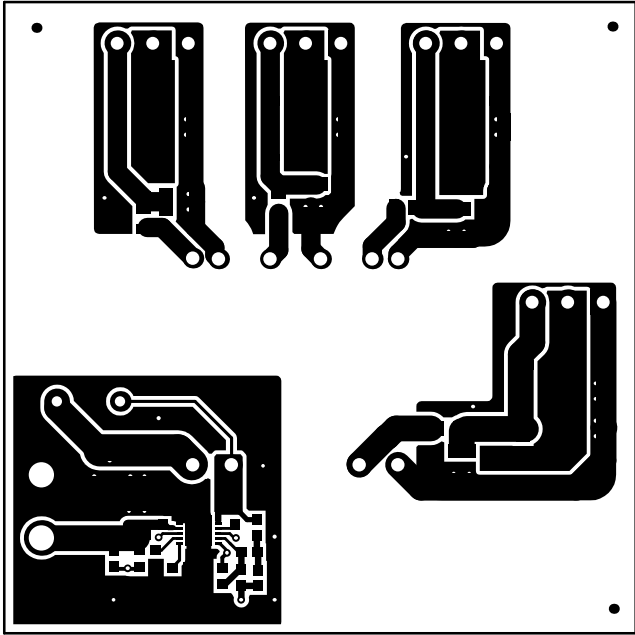

**TEXAS
INSTRUMENTS**
 PMP10531
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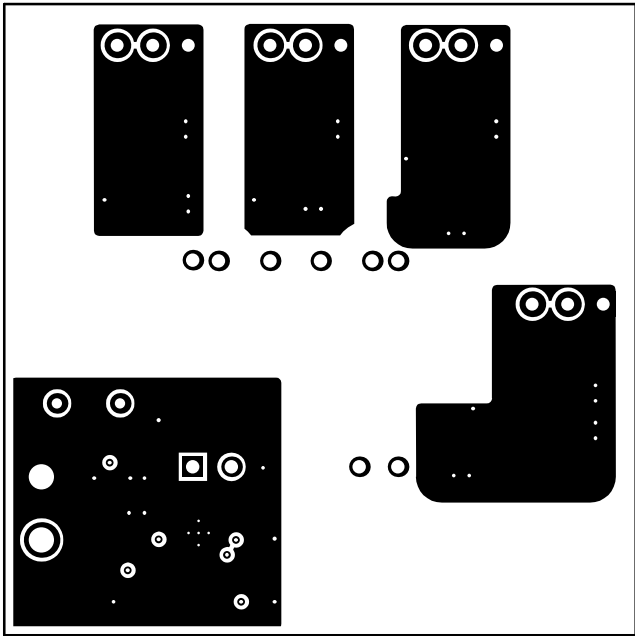
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10531	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/25/2014 2:10:24 PM	TEXAS INSTRUMENTS	



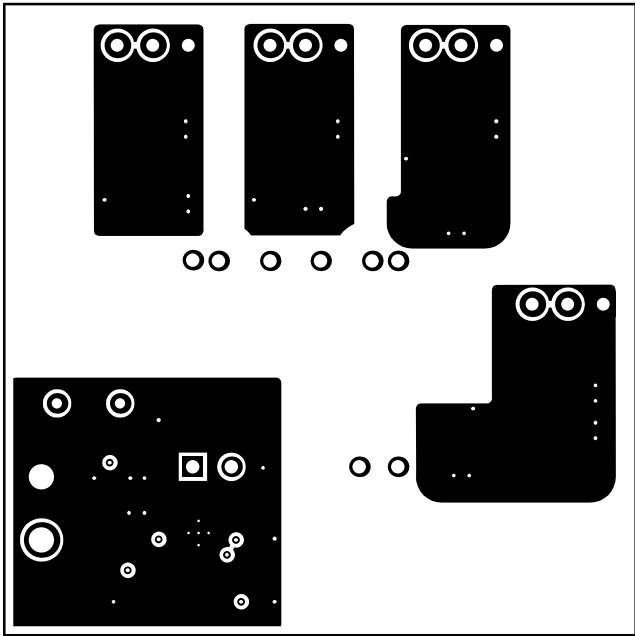
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LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/25/2014 2:10:25 PM	TEXAS INSTRUMENTS	



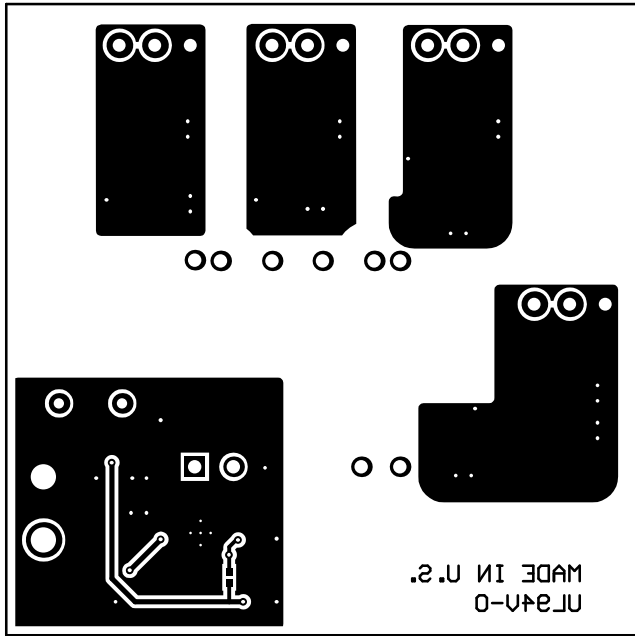
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LAYER NAME = Top Layer			
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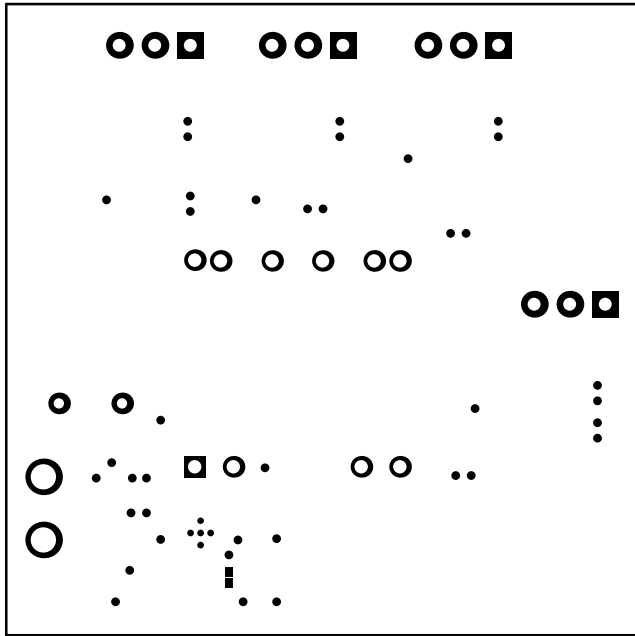
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LAYER NAME = MidLayer1			
PLOT NAME = Mid Plane 1	GENERATED : 11/25/2014 2:10:26 PM	TEXAS INSTRUMENTS	



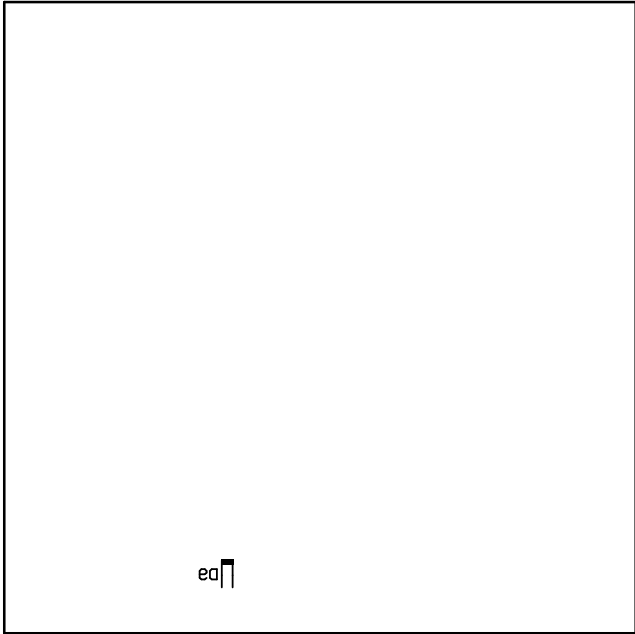
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LAYER NAME = MidLayer2			
PLOT NAME = Mid Plane 2	GENERATED : 11/25/2014 2:10:26 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10531	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/25/2014 2:10:27 PM	TEXAS INSTRUMENTS	



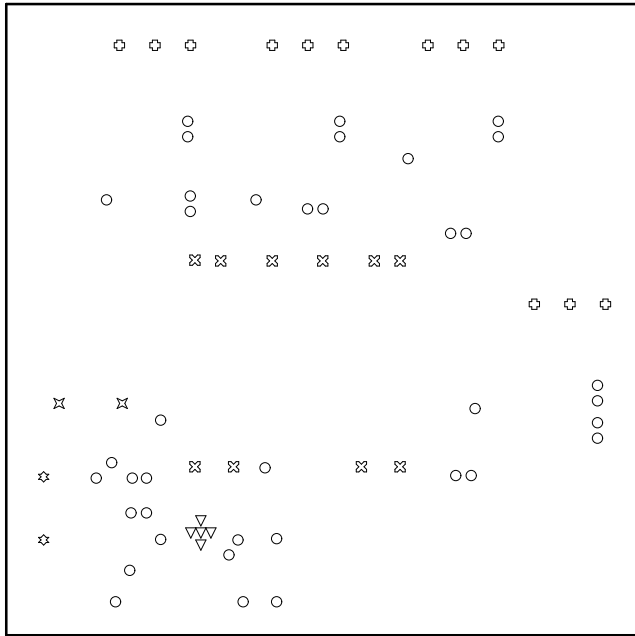
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10531	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/25/2014 2:10:28 PM	TEXAS INSTRUMENTS	



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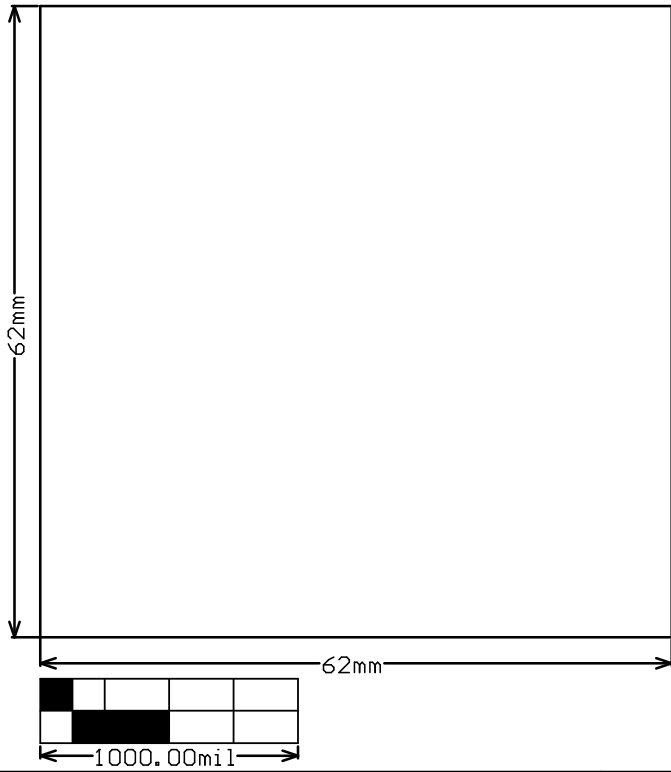
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10531	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/25/2014 2:10:28 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	5	10mil (0.254mm)	PTH	Round
○	38	15mil (0.381mm)	PTH	Round
✕	2	40mil (1.016mm)	PTH	Round
⊕	12	50mil (1.27mm)	PTH	Round
⊗	10	52mil (1.321mm)	PTH	Round
☆	2	98.425mil (2.5mm)	PTH	Round
	69 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10531	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/25/2014 2:10:29 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10531	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 11/25/2014 2:10:30 PM	TEXAS INSTRUMENTS	

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